

I HEREBY CERTIFY THAT THIS CORRESPONDENCE IS BEING FACSIMILE TRANSMITTED TO THE  
THE FOLLOWING DATE: June 28, 2002  
Depositor: Hilda Heinlein

RECEIVED  
CENTRAL FAX CENTER

APR 22 2004

OFFICIAL

\_\_\_\_\_  
Signature & Date

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE	
In re application of: <b>Lannie R. Bolde</b>	Date: <b>June 28, 2002</b>
Serial Number: <b>09/756,832</b>	Examiner: <b>ZIDIA T. PITTMAN</b>
Filed: <b>January 9, 2001</b>	Group Art Unit: <b>1725</b>
Title: <b>KNOWN GOOD DIE REMOVAL METHOD AND APPARATUS</b>	IBM Corporation D/18G, B/300, Zip 482 2070 Route 52 Hopewell Junction, NY 12533-6531

**AMENDMENT**

In response to the Office Action mailed March 29, 2002, the above-captioned application is amended as follows:

**In the claims:**

1. (Amended) A method for separating a semiconductor device from a substrate in a fixture having a shearing element where the semiconductor device is attached to the substrate by solder connections to form an assembly, the method comprising:

**FIS920000300US1**

**-1-**